



ADVANCED MICRO DEVICES, INC  
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17 May 2010

## REACH Compliance Statement for AMD Products

Dear AMD Customer:

REACH (Registration, Evaluation, Authorisation and restriction of CHemicals) was established by Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006, and established the ECHA (European Chemicals Agency) to regulate chemicals and their safe use.

The first list of SVHCs (Substance of Very High Concern) was published by the ECHA in 2008 and expanded in January 2010. AMD understands the ECHA plans to update (expand) the SVHC list up to twice per annum. Customers will be informed if and when any published SVHC are present in AMD products above a threshold limit of 0.1% (1,000 ppm).

### CPU, GPU, Chipset and Graphics Board Products:

As of the date of this statement, AMD CPUs, GPUs, Chipsets, and graphic boards do not contain any published SVHC above 0.1% (see below).

### External dongles and cables:

Certain third-party cables and dongles supplied with some graphic cards may contain the following substances on the published list above the threshold of 0.1 wt% (1,000 ppm):

- BBP (Benzyl butyl phthalate), CAS No 85-68-7, EC No 201-622-7,
- DBP (Dibutyl phthalate), CAS No 84-74-2, EC No 201-557-4,
- DEHP (Bis(2-ethylhexyl) phthalate), CAS No 117-81-7, EC No 204-211-0,
- HBCDD (Hexabromocyclododecane), CAS No 25637-99-4, EC No 247-148-4.

AMD products offered to end-customers since 2009 use cables free from the published (as of the date of this statement) SVHCs.

### Packaging:

- AMD shipments of ASIC (GPU, Chipsets, etc) to customers (manufacturers) previously included a HIC (humidity indicator card) which contains cobalt dichloride, CAS No 7646-79-9, EC No 231-589-4, a SVHC candidate, as the humidity indicator.

While our current HICs use an indicator not currently listed as an SVHC, older cards may be present in dry-bags previously packed or distributed.

- Other AMD products, which do not require customer mounting using solder reflow, (such as graphics boards), do not use HICs in shipment packaging.

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Should you wish additional information, please refer to our website at: [www.amd.com/rohs](http://www.amd.com/rohs), or contact us at: [customer.inquiry@amd.com](mailto:customer.inquiry@amd.com)

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If you have any further questions or concerns regarding AMD's product environmental compliance program, please contact us at the email address listed above.

Yours truly,

ADVANCED MICRO DEVICES, INC.

A handwritten signature in dark ink, appearing to read "H. E. Nariman".

H. E. Nariman  
Director, Quality Engineering

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